



Material Content Data Sheet



Sales Product Name	TLE4208G			Issued		28. August 2013		
MA#	MA000995364							
Package	PG-DSO-28-35			Weight*		835.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.786	1.41	1.41	14111	14111
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		87	
	non noble metal	zinc	7440-66-6	0.292	0.03		349	
	non noble metal	iron	7439-89-6	5.837	0.70		6988	
	non noble metal	copper	7440-50-8	237.007	28.38	29.12	283757	291181
wire	noble metal	gold	7440-57-5	1.065	0.13	0.13	1275	1275
encapsulation	organic material	carbon black	1333-86-4	1.136	0.14		1360	
	plastics	epoxy resin	-	52.239	6.25		62543	
	inorganic material	silicondioxide	60676-86-0	514.441	61.58	67.97	615915	679818
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5882	5882
plating	noble metal	silver	7440-22-4	1.897	0.23	0.23	2272	2272
glue	plastics	epoxy resin	-	1.140	0.14		1365	
	noble metal	silver	7440-22-4	3.421	0.41	0.55	4096	5461
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com